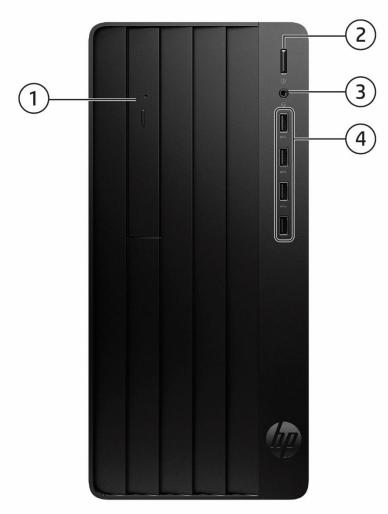
Overview

HP Pro Tower 290 G9 Desktop PC



- 1. Slim-height Bay supporting an optical disk drive (Optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- 4. (4) SuperSpeed USB 5Gbps signaling rate port¹

Not shown

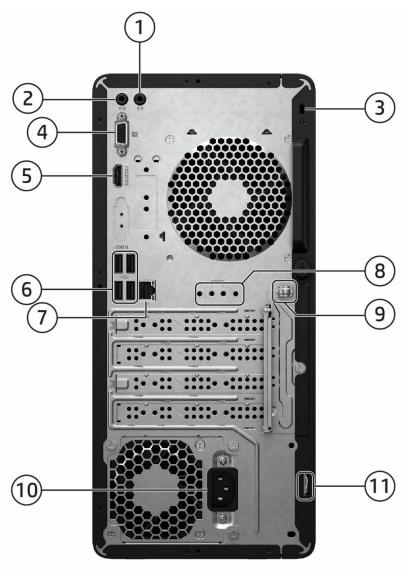
Slots	Bays
(1) PCI Express 4.0 x16 ²	(2) 3.5"
(1) PCI Express 3.0 x1	(1) 9.5mm internal optical drive bay

- (1) M.2 for WLAN
- (1) M.2 2242/2280 storage
- 1. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1.
- 2. Support discrete graphic cards and storage devices only.



Overview

HP Pro Tower 290 G9 Desktop PC



- 1. **Audio Line out**
- 2. Audio Line in
- Standard lock slot 3.
- 4. VGA Port1
- 5. HDM Port1
- Not shown
- (1) Parallel Port (Optional via PCIex1 slot)
- (1) 4 Serial Port (Optional via PCIex1 slot)3
- (1) Intrusion Sensor (Optional)
- 11.

Connector (4) USB 2.0 port

Integrated accessories cable lock

RJ-45 Network

Serial port (optional)

Power Cord Connector²

Padlock Loop

6.

7.

8.

9.

10.

- 1. Port will be covered up when configured with processor which is without internal graphics.
- 2. Power cord connector will be in different position, depends on which power supply configured.
- 3. Available in select countries only.

Overview

AT A GLANCE

- Windows 11 Pro 64, Win 11 Home 64, Win 11 Pro 64 Downgrade (Win 10 Pro 64) or FreeDOS.
- Intel® H670 or H770¹ chipset supporting Intel® 12th or 13th processors¹ featuring Intel® UHD Graphics.
- Supports an optional discrete graphics card.
- Integrated 10/100/1000 Ethernet Controller or ac 2x2 +Bluetooth 5 M.2 2230 PCI-e+USB WW or 802.11ac (1x1) Wi-Fi® and Bluetooth® 4.2 Combo or Realtek 8852BE Wi-Fi 6 +Bluetooth® 5.2 Screw WLAN
- Up to 64GB DDR4- 3200 Unbuffered Memory (UDIMM).
- Independent monitor support via VGA and HDMI interfaces.
- TPM2.0 support (PCI version support dTPM, and the non-PCI version support fTPM)¹.
- Supports both Hard Disk Drives and PCIe® NVMe™ M.2 SSD or PCIe® NVMe™ TLC M.2 SSD.
- Up to 10 USB Ports (including native 4 SuperSpeed USB 5Gbps signaling rate ports and 2 SuperSpeed USB 10Gbps signaling rate ports and 2 USB 2.0 ports).
- 180W/350W/500W 90% HE power supply and 260W 92% HE power supply.
- Security cable lock supported (sold separately).
- Intrusion sensor supported (Optional).
- Optional HP Services available²; terms and conditions vary by country; certain restrictions and exclusions apply.

1. Available on select skus only.

2. HP Services are optional. Service levels and response times for HP Care Services may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

PRODUCT NAME

HP Pro Tower 290 G9 Desktop PC

OPERATING SYSTEM

Preinstalled Windows 11 Pro¹

Windows 11 Home - HP recommends Windows 11 Pro for Business¹

Windows 11 Home Single Language - HP recommends Windows 11 Pro for Business¹

Windows 11 Pro (preinstalled with Windows 10 Pro Downgrade)^{1,2}

FreeDOS

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- 2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.



Standard Features and Configurable Modules

PROCESSORS

Intel® Celeron® Processors1,2

CPU Intel Celeron G6900 Dual Core 3.4GHz 3200MHz 46W (3.4GHz, 4MB cache, 2 cores)

Intel® Pentium® Processors^{1,2}

CPU Intel Pentium Gold G7400 Dual Core 3.7GHz 3200MHz 46W (3.7GHz, 6MB cache, 2 cores)

Intel 12th Processors

Intel® Core™ i31

CPU Intel Core i3-12100 4C 3.3GHz 3200MHz 60W (3.3GHz, turbo up to 4.3GHz, 12MB cache, 4 cores)

Intel® Core™ i51

CPU Intel Core i5-12400 6C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.4GHz, 18MB cache, 6 cores) CPU Intel Core i5-12500 6C 3.0GHz 3200MHz 65W (3.0GHz, turbo up to 4.6GHz, 18MB cache, 6 cores)

Intel® Core™ i71

CPU Intel Core i7-12700 12C 2.1GHz 3200MHz 65W (2.1GHz, Up to 4.8GHz with Intel® Turbo Boost², 25MB cache, 12 cores)

Intel 13th Processors

Intel® Core™ i31

CPU Intel Core i3-13100 4C 3.4GHz 3200MHz 60W (3.4GHz, turbo up to 4.5GHz, 12MB cache, 4 cores)

Intel® Core™ i51

CPU Intel Core i5-13400 10C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.6GHz, 20MB cache, 10 cores) CPU Intel Core i5-13500 14C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.8GHz, 24MB cache, 14 cores)

Intel® Core™ i71

CPU Intel Core i7-13700 16C 2.1GHz 3200MHz 65W (2.1GHz, Up to 5.2GHz with Intel® Turbo Boost², 30MB cache, 16 cores)

1. Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

2. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information.



Standard Features and Configurable Modules

CHIPSET

Intel® H670/H770 Chipset

GRAPHICS

Integrated^{1,2}

Intel® UHD

Graphics 770

Graphics 730

Graphics 710

Discrete Graphics

AMD Radeon™ RX 6600XT Graphics (8 GB GDDR6)

AMD Radeon™ RX 6400 Graphics (4 GB GDDR6)

AMD Radeon™ RX 6300 Graphics (2 GB GDDR6)

NVIDIA® Quadro® T400 (4 GB GDDR6 dedicated)

NVIDIA® GeForce RTX 3050 Graphics (8 GB GDDR6)

NVIDIA® GeForce RTX 4060 Graphics (8 GB GDDR6)

- 1. HD content required to view HD images.
- 2. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.
- *NOTE: Available in select countries only.

MEMORY

Form Factor Type Maximum # of Slo				
Tower	ower DDR4 3200 64 GB capacity 2 DIM			
4GB DDR4-3200 UDIMM NECC (1x4GB)				
8GB DDR4-3200 UDIMN	1 NECC (1x8GB)			
8GB DDR4-3200 UDIMN	1 NECC (2x4GB) ²			
16GB DDR4-3200 UDIM	IM NECC (1x16GB)			
16GB DDR4-3200 UDIM	IM NECC (2x8GB) ²			
32GB DDR4-3200 UDIM	IM NECC (1x32GB)			
32GB DDR4-3200 UDIMM NECC (2x16GB) ²				
64GB DDR4-3200 UDIM	IM NECC (2x32GB)²			

^{1.} Memory modules support data transfer rates up to 2933 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.



^{2.} Memory speed 3200 MT/s can be achieved via two UDIMMs per channel (2DPC) when populated with the same part number. **NOTE:** DDR4-2933 UDIMM is only available for 10th Gen i7 processor.

Standard Features and Configurable Modules

STORAGE

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

SATA3 - 3.5" or 2.5" 6Gb/s HDDs

2TB 7200 RPM SATA Hard Disk Drive 1TB 7200 RPM SATA Hard Disk Drive 500GB 7200 RPM SATA Hard Disk Drive

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

Solid State Drives

256GB* M.2 NVMe

512GB* M.2 NVMe

1TB* M.2 NVMe

128GB* M.2 2230 PCIe NVMe*

128GB* M.2 2280 PCIe NVMe Three Layer Cell SSD

256GB* M.2 2280 PCIe NVMe Three Layer Cell SSD

512GB* M.2 2280 PCIe NVMe Three Layer Cell SSD

1TB* M.2 2280 PCIe NVMe Three Layer Cell SSD

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

*NOTE: Available in select countries only.

OPTICAL DISC DRIVES

DVD-ROM 9.5mm DVD-Writer¹ 9.5mm

1. HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Standard Features and Configurable Modules

NETWORKING¹

Ethernet (RJ-45)

Integrated 10/100/1000M GbE LAN

Wi-Fi® and Bluetooth®

Realtek RTL8852BE Wi-Fi6+ Bluetooth® 5.2
Realtek RTL8822CE-CG 802.11a/b/g/n/ac (2x2) with Bluetooth® M.2 PCIe®
Realtek RTL8821CE-CG 802.11a/b/g/n/ac (1x1) with Bluetooth® M.2 PCIe®

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

NOTE: Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.

AUDIO / MULTIMEDIA

Realtek ALC3867-CG Integrated Hi-Definition Audio Combo Jack, Headphone / Microphone Line-in / Line-out (3.5mm)

KEYBOARDS AND POINTING DEVICES¹

Keyboard

HP USB 320K Keyboard
HP 125 BLK Wired Keyboard
HP 125 Antimicrobial Wired Keyboard (china only)
HP PS/2 Business Slim Keyboard (for machine configured with PS/2 port)

Mouse

HP PS/2 mouse (for machine configured with PS/2 port)
HP Wired Desktop 320M mouse
HP 125 Wired Mouse
HP 128 Laser Wired Mouse
HP 125 Antimicrobial Wired Mouse (china only)

1. Keyboards and mouse are optional or add-on features. A keyboard and mouse are required for this device. If you do not already have a keyboard and mouse, please refer to a list of compatible keyboards on the "Recommended Accessories" page.

PORTS

Front

Slim-height Bay - supporting an optical disk drive (Optional)
Power Button
Combo jack, Headphone / Microphone
(4) SuperSpeed USB 5Gbps port*



Standard Features and Configurable Modules

Not shown

- (1) PCI Express 4.0 x16
- (1) PCI Express 3.0 x1
- (1) Full-height PCI (Available on selected sku)
- (1) M.2 for WLAN
- (1) M.2 2230/2280 storage

Rear

Audio Line out

Audio Line in

HDMI Port

VGA Port

Standard Lock Slot

(4) USB 2.0 port (Optional on selected sku)

RJ-45 Network connector

Power cord connector

Padlock loop

Integrated accessories cable lock

Serial port (optional)

Not shown

- (1) Parallel Port (Optional via PCIex1 slot)
- (1) 4x Serial port (Optional via PCIex1 slot)*
- (1) Intrusion Sensor (Optional)

NOTE*: Available in select countries only.

NOTE**: SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

BAYS

- (1) 9.5mm external slimline ODD bay (Optional)
- (1) 3.5" internal HDD or bay
- (1) 3.5" internal HDD bay (share bay with caddy)



Standard Features and Configurable Modules

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection

McAfee* LiveSafe™1

Productivity

Microsoft 365²

Xerox® DocuShare® (90 days free trial offer)3

ODD Playback

sMedio True DVD for HP

Movies

Netflix4

App Stores and Content Purchasing

Amazon⁴

HP Utilities and Support

HP Documentation HP Audio Switch⁵ HP Support Assistant myHP

BTB

HP Setup Integrated 00BE

Hardware Enabling Drivers or software utility

HP System Event Utility

- 1. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration
- 2. Sold separately and requires Internet access for activation.
- 3. Simply sign up and start using Xerox® DocuShare® Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 day free trial period. See visit https://http://www.xerox.com/docusharego for details.
- 4. Internet access required and not included.
- 5. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience.
- *NOTE: Available in Latin America countries only.

POWER SUPPLY¹

180 W

EPA90 (Gold) +12V

260W

EPA92 +12V

350 W

EPA90 (Gold) Power Supply

500 W

EPA90 (Gold) Full range 115V/230V

1. All power supplies are not available in every region.



Standard Features and Configurable Modules

DIMENSIONS AND WEIGHT

Dimensions

6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm)

Weight

10.4 lbs / 4.7 kg

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit
 is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 5° to 35° C¹

Non-operating: -30° to 60° C1

Relative Humidity Operating: 5% to 90% (non-condensing at ambient)

Non-operating: 5% to 90% (non-condensing at ambient)

Maximum Altitude (unpressurized) Operating: 5000 m

Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

This product has received or is in the process of being certified to the following approvals and may be
labeled with one or more of these marks:
• IT ECO declaration
• US ENERGY STAR®
US Federal Energy Management Program (FEMP)
• EPEAT® Gold* or EPEAT Silver** registered in the United States. See http://www.epeat.net for
registration status in your country.
China Energy Conservation Program (CECP)
China State Environmental Protection Administration (SEPA)
Taiwan Green Mark
Commission Regulation (EC) No 617/2013 (ErP Lot 3)
Note*: Only available on 13th Gen CPU Legacy SKU, except Japan.
Note**: Available on all 12th Gen CPU SKUs, 13th Gen non-legacy SKUs, and 13th Gen legacy SKUs for Japan.
Product Carbon Footprint (hp.com)
30% post-consumer recycled plastic
• Low halogen
Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable.
Bulk packaging available



Standard Features and Configurable Modules

		gy Consumption and Declared No	oise Emissions data for the
Energy Consumption (in accordance with US ENERGY STAR® test method)	Desktop model is based on a "Typic 115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	16.34 W 17.06 W		16.41 W
Normal Operation (Long idle)	16.31 W 16.04 W		16.15 W
Sleep	1.74 W	1.73 W	1.76 W
Off	0.32 W	0.33 W	0.32 W
Hoot Dissipation*	NOTE: Energy efficiency data listed is for family. HP computers marked with the Environmental Protection Agency (EPA) offer ENERGY STAR® compliant configure featuring a hard disk drive, a high efficients.	ENERGY STAR® Logo are compliant w DENERGY STAR® specifications for co rations, then energy efficiency data l ency power supply, and a Microsoft V	vith the applicable U.S. mputers. If a model family does not iisted is for a typically configured PC Windows® operating system.
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	55.72 BTU/hr	58.17 BTU/hr	55.96 BTU/hr
Normal Operation (Long idle)	55.62 BTU/hr	54.70 BTU/hr	55.07 BTU/hr
Sleep Off	5.93 BTU/hr 1.09 BTU/hr	5.90 BTU/hr 1.13 BTU/hr	6.00 BTU/hr 1.09 BTU/hr
	NOTE: Heat dissipation is calculated bas	sed on the measured watts, assumin	g the service level is attained for on
Emissions	hour. Sound Power	sed on the measured watts, assumin	g the service level is attained for on Sound Pressure
Emissions (in accordance with ISO 7779 and ISO 9296)	hour.	sed on the measured watts, assumin	-
Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle	hour. Sound Power	sed on the measured watts, assumin	Sound Pressure
Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes	Sound Power (LwAd, bels)	sed on the measured watts, assumin	Sound Pressure (L _{pAm} , decibels)
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes Optical Drive – Sequential reads	Sound Power (LwAd, bels) 3.6 3.7 3.8		Sound Pressure (L _{pAm} , decibels) 25 26 26
Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes Optical Drive –	Sound Power (LwAd, bels) 3.6 3.7	sibly extending its useful life by so ined in the product may include:	Sound Pressure (L _{pAm} , decibels) 25 26 26 everal years. Upgradeable
Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes Optical Drive – Sequential reads	Sound Power (LwAd, bels) 3.6 3.7 3.8 This product can be upgraded, poss features and/or components contains. Spare parts are available throughout.	sibly extending its useful life by so ined in the product may include: ut the warranty period and or for oly with EU Directive 2006/66/EC t contain: t	Sound Pressure (LpAm, decibels) 25 26 26 everal years. Upgradeable



Standard Features and Configurable Modules

Additional Information	• This produ	ct is in compliance with the Restrictions of Hazardous Sub	stances (RoHS) directive -
	2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE Directive – 2002/96/EC.		
			Electronic Equipment (WEEE)
		ct is in compliance with California Proposition 65 (State of	California: Safe Drinking Water
		forcement Act of 1986).	
		ct is in compliance with the IEEE 1680.1 (EPEAT) standard	at the Gold level, see
	http://www.epeat.net		
	 Plastics pa 	rts weighing over 25 grams used in the product are marke	d per IS011469 and IS01043.
	 This produ 	ct contains 28.2% post-consumer recycled plastic (by wt.)	
		ct is 92.9% recycle-able when properly disposed of at end	of life.
Packaging Materials	External:	PAPER/Paperboard	1220 g
	Internal:	PAPER/Molded Pulp	580 g
		PLASTIC/Polyethylene low density - LDPE	40 g
	The plastic	packaging material contains at least 0.0% recycled conten	t.
	The corrugated paper packaging materials contains at least 35.0% recycled content.		cycled content.
	HP Inc. com	olies fully with materials regulations. We were among the	first companies to extend the
	restrictions	in the European Union (EU) Restriction of Hazardous Subs	tances (RoHS) Directive to our
		orldwide through the HP GSE. HP has contributed to the de	velopment of related
	legislation i	n Europe, as well as China, India, and Vietnam.	
	We believe t	he RoHS directive and similar laws play an important role	in promoting industry-wide
		of substances of concern. We have supported the inclusio	
		/C, BFRs, and certain phthalates—in future RoHS legislatio	
	_	nics products.	
	We met our	voluntary objective to achieve worldwide compliance with	the new EU RoHS
		ts for virtually all relevant products by July 2013, and we v	
	scope of the	commitment to include further restricted substances as i	regulations continue to evolve.
	To obtain a	copy of the HP RoHS Compliance Statement, see HP RoHS	position statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refe		ss of regulatory limits (refer to
		ral Specification for the Environment at hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pd	df).
	• Asbestos	np.com/npinro/globalcitizensnip/environment/pui/gse.p	ur).
	Certain Azo	Colorants	
		ominated Flame Retardants – may not be used as flame re	tardants in plastics
	• Cadmium	minuted rame netardants may not be ased as name re	tardants in plastics
		d Hydrocarbons	
	 Chlorinate 		
	 Formaldeh 		
		ed Diphenyl Methanes	
	• Lead carbo	nates and sulfates	
	 Lead and L 	ead compounds	
		xide Batteries	
		ishes must not be used on the external surface designed t	to be frequently handled or
	carried by th		
		leting Substances	
	-	nated Biphenyls (PBBs)	
		nated Biphenyl Ethers (PBBEs)	
		nated Biphenyl Oxides (PBBOs)	
		nated Biphenyl (PCB)	
		nated Terphenyls (PCT)	tail packaging has been
		hloride (PVC) – except for wires and cables, and certain re	tait packaying nas been
	voluntarily f	emoved from most applications.	



Standard Features and Configurable Modules

crease the environmental impact of product packaging: als such as lead, chromium, mercury and cadmium in packaging leting substances (ODS) in packaging materials. ease of disassembly. mer recycled content materials in packaging materials. g materials such as paper and corrugated materials. ages to improve transportation fuel efficiency. marked according to ISO 11469 and DIN 6120 standards. uct return and recycling programs in many geographic areas. To b: http://www.hp.com/go/reuse-recycle or contact your nearest HP HP will be recycled, recovered or disposed of in a responsible	
eting substances (ODS) in packaging materials. ease of disassembly. mer recycled content materials in packaging materials. g materials such as paper and corrugated materials. eages to improve transportation fuel efficiency. marked according to ISO 11469 and DIN 6120 standards. uct return and recycling programs in many geographic areas. To b: http://www.hp.com/go/reuse-recycle or contact your nearest HP	
Leting substances (ODS) in packaging materials. ease of disassembly. mer recycled content materials in packaging materials. g materials such as paper and corrugated materials. eages to improve transportation fuel efficiency. marked according to ISO 11469 and DIN 6120 standards. uct return and recycling programs in many geographic areas. To b: http://www.hp.com/go/reuse-recycle or contact your nearest HP	
ease of disassembly. mer recycled content materials in packaging materials. g materials such as paper and corrugated materials. ages to improve transportation fuel efficiency. marked according to ISO 11469 and DIN 6120 standards. uct return and recycling programs in many geographic areas. To b: http://www.hp.com/go/reuse-recycle or contact your nearest HP	
mer recycled content materials in packaging materials. g materials such as paper and corrugated materials. ages to improve transportation fuel efficiency. marked according to ISO 11469 and DIN 6120 standards. uct return and recycling programs in many geographic areas. To b: http://www.hp.com/go/reuse-recycle or contact your nearest HP	
g materials such as paper and corrugated materials. ages to improve transportation fuel efficiency. marked according to ISO 11469 and DIN 6120 standards. uct return and recycling programs in many geographic areas. To b: http://www.hp.com/go/reuse-recycle or contact your nearest HP	
marked according to ISO 11469 and DIN 6120 standards. uct return and recycling programs in many geographic areas. To b: http://www.hp.com/go/reuse-recycle or contact your nearest HP	
marked according to ISO 11469 and DIN 6120 standards. uct return and recycling programs in many geographic areas. To b: http://www.hp.com/go/reuse-recycle or contact your nearest HP	
uct return and recycling programs in many geographic areas. To b: http://www.hp.com/go/reuse-recycle or contact your nearest HP	
o: http://www.hp.com/go/reuse-recycle or contact your nearest HP	
manner.	
EC) requires manufacturers to provide treatment information for tment facilities. This information (product disassembly instructions) web site at: http://www.hp.com/go/recyclers. These instructions er WEEE treatment facilities as well as HP OEM customers who nnt. alcitizenship/gcreport/index.html	
r	

SERVICE AND SUPPORT

On-site Warranty¹: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day² service for parts and labor and complimentary limited technical support³. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack⁴ To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

- 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3: Technical support applies only to HP-configured and third-party HP qualified hardware and software.
- 4: Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications - Graphics

GRAPHICS

Intel® UHD Graphics (integrate	ed)	
Graphics Controller	Integrated	
DisplayPort™	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 4 displays connected to any output controlled by Intel® Graphics	
НОМІ	Supports HDMI 2.0a features Supports HDCP 2.2 Supports audio over HDMI	
VGA	VGA output	
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.	
Maximum Color Depth	up to 10 bits/color	
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12	
Supported Display Resolutions and Refresh Rates	Max. Resolution (VGA) 2048 x 1536 @60Hz Max. Resolution (HDMI) 7680 x 4320 @60Hz	

Note: The actual amount of maximum graphics memory can be less than the amounts listed above depending upon your computer's configuration.

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP Only supported on displays connected to the external DisplayPort™ connector.

AMD Radeon™ RX 6300 4GB Graphics Card

Engine Clock 1512MHz (Game) 2040MHz (Boost)

Memory Clock2000 MHzMemory Size(width)2GB (64-bit)Memory Type512M x 32 GDDR6

 Max. Resolution (HDMI)
 7680 x 4320x 36bpp@60Hz

 Max. Resolution (DP)
 7680 x 4320 x 24bpp@120Hz

Multi Display Support 2 displays

HDCP Compliance Yes

Rear I/O connectors (bracket) HDMI+DP

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 32W

PCB form-factor with bracket LP PCB with FH/LP bracket



Technical Specifications - Graphics

AMD Radeon™ RX 6400 4GB Graphics Card

 Engine Clock
 1923MHz

 Memory Clock
 2000MHz

 Memory Size(width)
 4GB (64-bit)

 Memory Type
 512M x 32 GDDR6

 Max. Resolution (HDMI)
 7680 x 4320@60Hz

 Max. Resolution (DP)
 7680 x 4320@60Hz

Multi Display Support 2 displays

HDCP Compliance yes

Rear I/O connectors (bracket) HDMI+DP

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ RX6600XT 8 GB Graphics Card

 Engine Clock
 1280MHz

 Memory Clock
 1000MHz

 Memory Size(width)
 8GB (128-bit)

 Memory Type
 512M x 32 GDDR6

 Max. Resolution (HDMI)
 7680 x 4320@60Hz

 Max. Resolution (DP)
 7680 x 4320@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors (bracket) HDMI+DPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 162.5W

PCB form-factor with bracket FH PCB with FH bracket

NVIDIA® Quadro T400 Graphics Card

 Engine Clock
 2100MHz

 Memory Clock
 5001MHz

 Memory Size (width)
 4GB (64-bit)

 Memory Type
 256M x 16 GDDR6

 Max. Resolution (DP)
 7680 x 4320@60Hz

Multi Display Support4 displaysHDCP ComplianceYesRear I/O connectors (bracket)mDPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 30W

PCB form-factor with bracket LP PCB with LP bracket



Technical Specifications - Graphics

NVIDIA® GeForce RTX 3050 8GB Graphics Card

 Engine Clock
 1515MHz

 Memory Clock
 7000MHz

 Memory Size (width)
 8GB (128-bit)

 Memory Type
 512M x 32 GDDR6

 Max. Resolution (DP)
 7680 x 4320@60Hz

 Multi Display Support
 7680x4320@60Hz (DSC)

HDCP Compliance Up to 4 displays

Rear I/O connectors (bracket) Yes

Cooling (active/passive) DPx3+ HDMIx1

Total power consumption (W) Active fansink with 4 pin fan control

PCB form-factor with bracket 120W

NVIDIA® GeForce RTX 4060 8GB Graphics Card

 Engine Clock
 1830Mhz

 Memory Clock
 17Gbps

 Memory Size (width)
 8GB (128-bit)

 Memory Type
 512M x 32 GDDR6

 Max. Resolution (DP)
 7680 x 4320@60Hz

 Multi Display Support
 7680 x 4320@60Hz

 HDCP Compliance
 Up to 4 displays

Rear I/O connectors (bracket) Yes

Cooling (active/passive) DPx3+ HDMIx1

Total power consumption (W) Active fansink

PCB form-factor with bracket 115W



Technical Specifications – Optical Drives

STORAGE*

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

HP 2TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 2TB

Rotational Speed 7,200 rpm Interface SATA 6Gb/s NCQ

Buffer Size 64MB

Logical Blocks 3,907,029,168 **Seek Time** Read: <8.5 ms

Write: <9.5 ms

Height 1.028 in/26.11 mm Width 4.0 in/101.6 mm

Operating Temperature 32° to 140° F (0° to 60° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 1TB

Rotational Speed 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 32MB

Logical Blocks 1,953,525,168 **Seek Time** Single Track: 2.0 ms Average: 11 ms

Full-Stroke: 21 ms

Height 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

500GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity 500GB **Rotational Speed** 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 32MB

Logical Blocks 1.953,525,168 **Seek Time** Single Track: 2.0 ms Average: 11 ms





Technical Specifications – Optical Drives

Full-Stroke: 21 ms

Height 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q 128GB Capacity Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2800MB/s **Maximum Sequential Write** Up to 600MB/s **Logical Blocks** 250.069.680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10g Capacity 256GB Height 2.38mm 80mm Length Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2700MB/s **Maximum Sequential Write** Up to 1000MB/s

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

500,118,192

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Logical Blocks

Technical Specifications — Optical Drives

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10g
Capacity 512GB
Height 2.38mm
Length 80mm
Width 22mm

InterfacePCIE Gen3x4Maximum Sequential ReadUp to 2900MB/sMaximum Sequential WriteUp to 1100MB/sLogical Blocks1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10g
Capacity 256GB
Height 2.38mm
Length 80mm
Width 22mm
Interface PCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 780MB/sLogical Blocks500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

512GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</td>Capacity512GBHeight2.38mmLength80mmWidth22mmInterfacePCIE Gen3

Maximum Sequential ReadUp to 1600MB/sMaximum Sequential WriteUp to 860MB/sLogical Blocks1,000,215,216



Technical Specifications — Optical Drives

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

500GB 7200RPM 2.5in SATA HDD

Capacity500GBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size32MB

Logical Blocks 976,773,168 **Seek Time** 12 ms (Average)

Height0.267 in/6.8 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity 1TB

Rotational Speed 7,200 rpm **Interface** SATA 6 Gb/s **Buffer Size** 32MB

Logical Blocks 1,953,525,168
Seek Time 12 ms (Average)

Height0.374 in/9.5 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

128GB M.2 2230 PCIe NVMe SSD

Drive Weight < 10q Capacity 128GB Height 2.3mm Length 30mm Width 22mm Interface **PCIE NVMe Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 780MB/s **Logical Blocks** 290,069,680

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features Pyrite



HP Pro Tower 290 G9 Desktop PC

QuickSpecs

Technical Specifications — Optical Drives

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Technical Specifications – Optical Drives

OPTICAL DISC DRIVES

HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g)

Read Speeds DVD-R DL Up to 6X

Up to 8X DVD+R DVD+RW Up to 8X DVD+R DL Up to 6X DVD-R Up to 8X **DVD-RW** Up to 6X CD-R Up to 24X CD-RW Up to 10X DVD-RW. DVD+RW Up to 8X DVD-R DL, DVD+R DL Up to 8X DVD+R, DVD-R Up to 8X DVD-ROM DL, DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X

CD-RW Up to 24X **Access time** Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

(typical reads, including Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) settling) Stop Time 6 seconds (typical)

Power Source Slimline SATA DC power receptacle

> DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions Temperature 41° to 122° F (5° to 50° C) (operating - non-condensing) Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

Technical Specifications — Optical Drives

HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

SATA/ATAPI Interface type

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g)

DVD-R DL **Read Speeds** Up to 6X

Up to 8X DVD+R Up to 8X DVD+RW DVD+R DL Up to 6X DVD-R Up to 8X **DVD-RW** Up to 6X CD-R Up to 24X CD-RW Up to 10X DVD-RW, DVD+RW Up to 8X DVD-R DL, DVD+R DL Up to 8X Up to 8X DVD+R, DVD-R DVD-ROM DL, DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) **Access time** Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

(typical reads, including

settling) Stop Time 6 seconds (typical)

Power Source Slimline SATA DC power receptacle

> DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Temperature 41° to 122° F (5° to 50° C) **Environmental conditions**

Relative Humidity 10% to 80% (operating - non-condensing)

Maximum Wet Bulb Temperature 84° F (29° C)



Technical Specifications – Networking

NETWORKING

10/100/1000 NIC	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	Power	ACPI compliant – multiple power modes
	Management	Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Performance	TCP/IP/UDP Checksum Offload (configurable)
	Features	Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30) Comprehensive diagnostic and configuration software suite
		Virtual Cable Doctor for Ethernet cable status
	Interface	PCIe + SMBus
	NIC Device Driver Name	PCIe GBE Ethernet Family Controller
		·

Realtek 802.11ac (1x1) Wi	-Fi 5 and Bluetooth ^o	[®] 4.2 Combo
Wireless LAN Standards ¹	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.	
Interoperability	Wi-Fi® certified modules	
Frequency Bands	802.11b/g/n	2.402 – 2.482 GHz NOTE: The FCC has declared products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 & 15.249 or otherwise disable those channels.
	802.11a/n	4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz



Data Rates	802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)	
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ²	IEEE and 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI	
	2 Check latest software/driver release for updates on supported security features.	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ³	802.11b: +14dBm minimum 802.11g: +12dBm minimum 802.11a: +12dBm minimum 802.11n HT20(2.4GHz): +12dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum 802.11n HT40(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum	
Power Consumption	•Transmit mode2.0 W •Receive mode1.6 W •Idle mode (PSP)180 mW(WLAN Associated) •Idle mode50 mW(WLAN unassociated) •Connected Standby 10mW •Radio disabled8 mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	



Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum		
	802.11b, 11Mbps: -84dBm maximum		
	802.11a/g, 6Mbps: -86dBm maximum		
	802.11a/g, 54Mbps: -72dBm maximum		
	802.11n, MCS07: -67dBm maximum		
	802.11n, MCS15: -64dBm maximum		
	802.11ac, MCS0: -84dBm maximum		
	802.11ac, MCS9: -59dBm maximum		
	4 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth ^a communications		
Form Factors	PCI-Express M.2 MiniCard		
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)		
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
HP Integrated Module with Blue	tooth® 4.0/4.1/4.2 Wireless Card Technol	ogy	
Bluetooth ^a Specification	4.0/4.1/4.2 Wireless Card Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps		
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels		
	Legacy: Asynchronous Connection Less li 864 kbps symmetric (3-EV5)	nks 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or	
Transmit Power	The Bluetooth® component shall operate transmit power of + 4 dBm for BR and ED	as a Class II Bluetooth® device with a maximum R.	



Receiver Sensitivity Legacy			
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Range	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Electrical Interface	USB 2.0 compliant		
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark		
Certifications Bluetooth ^a Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support		
Certifications Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		



Realtek RTL8822CE 802.11	ac 2x2 Wi-Fi® + Bluetooth® 5		
Wireless LAN Standards	IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac IEEE 802.11d IEEE 802.11e		
	IEEE 802.11h		
	IEEE 802.11i		
	IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
Interoperability	Wi-Fi® certified		
Frequency Band	802.11b/g/n		
	• 2.402 – 2.482 GHz		
	802.11a/n/ac		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)		
	, , , , , , , , , , , , , , , , , , , ,		
Modulation	Direct Sequence Spread Spectrum		
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ¹	• IEEE and Wi-Fi® compliant 64 / 128 bit WEP encryption for a/b/g mode only		
	AES-CCMP: 128 bit in hardware		
	• 802.1x authentication		
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.		
	WPA2 certification		
	• IEEE 802.11i		
	• WAPI		
	1 Check latest software/driver release for updates on supported security features.		
Network Architecture Models	Ad-hoc (Peer to Peer)		
	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
	in the control of the		



LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON	
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)	
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)	
Temperature	Operating: 14° to 158° F (–10° to 70° C) Non-operating: –40° to 176° F (–40° to 80° C)	
Operating Voltage	3.3v +/- 9%	
Veight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	3 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).	
	802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum	
	802.11n, MCS0767dBiri maximum 802.11n, MCS15: -64dBm maximum	
	802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum	
	802.11a/g, 6Mbps: -86dBm maximum	
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum	
_	802.11 compliant power saving mode	
Power Management	ACPI and PCI Express compliant power management	
	• Radio disabled: 8 mW	
	 Idle mode:50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW 	
	• Idle mode (PSP) 180 mW (WLAN Associated)	
Power Consumption	Transmit mode:2.0 W Receive mode:1.6 W	
	2. Maximum output power may vary by country according to local regulations.	
	• 802.11ac VHT160(5GHz): +11.5dBm minimum	
	• 802.11ac VHT80(5GHz): +11.5dBm minimum	
	 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 	
	• 802.11n HT40(2.4GHz): +14.5dBm minimum	
	• 802.11n HT20(2.4GHz): +15.5dBm minimum	
	• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum	



Bluetooth Specification	4.0/4.1/4.2/5.0 Wireless Card Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.		
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW		
Bluetooth Software Supported	Microsoft Windows Bluetooth Software		
Link Topology			
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950-1/IEC62368-1 UL, CSA, and CE Mark		
Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 – Link Layer Privacy LE Privacy 1.2 – Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		



Realtek RTL8852BE Wi-Fi6	+ Bluetooth® 5.2		
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11t IEEE 802.11t IEEE 802.11h IEEE 802.11i IEEE 802.11i IEEE 802.11r IEEE 802.11r		
Interoperability	Wi-Fi certified		
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n/ac • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz		
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz) 		
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI 1 Check latest software/driver release for updates on supported security features. 		
Network Architecture Models			
Roaming	IEEE 802.11 compliant roaming between access points		



LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON		
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)		
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)		
•	Non-operating: -40° to 176° F (-40° to 80° C)		
Temperature	Operating: 14° to 158° F (–10° to 70° C)		
Operating Voltage	2. Type 126: 1.3g 3.3v +/- 9%		
Weight	1. Type 2230: 2.8g		
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface		
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure		
	3 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).		
	802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum		
	802.11n, MCS15: -64dBm maximum		
	802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum		
	802.11a/g, 6Mbps: -86dBm maximum		
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum		
_	802.11 compliant power saving mode		
Power Management	ACPI and PCI Express compliant power management		
	• Radio disabled: 8 mW		
	Idle mode:50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW		
	• Idle mode (PSP) 180 mW (WLAN Associated)		
Power Consumption	Transmit mode:2.0 W Receive mode:1.6 W		
	2. Maximum output power may vary by country according to local regulations.		
	 802.11ac VHT80(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum 		
	• 802.11n HT40(5GHz): +14.5dBm minimum		
	• 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum		
	• 802.11n HT20(2.4GHz): +15.5dBm minimum		
	• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum		
Output Power ²	• 802.11b: +18.5dBm minimum		



Bluetooth Specification	4.0/4.1/4.2/5.0 Wireless Card Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.		
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW		
Bluetooth Software Supported	Microsoft Windows Bluetooth Software		
Link Topology			
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950-1/IEC62368-1 UL, CSA, and CE Mark		
Bluetooth® Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		



Technical Specifications - Audio

HIGH DEFINITION AUDIO

Type Integrated

HD Stereo Codec Realtek ALC3867-CG

Audio I/O Ports Front side Combo jack for supporting CTIA, Rear side Line-in/ Line-out/ Mic-in jacks

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally.

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

HD Audio Codec Realtek ALC3601

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1K/

48 K/96K / 192K Hz for DAC and 44.1K/ 48K/ 96K/ 192K Hz Hz for ADC

Wavetable Syntheses Yes
Analog Audio Yes
of Channels on Line-Out Stereo
Internal Speaker Yes

External Speaker Jack* 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally.

NOTE*: Optional



Technical Specifications - Power

POWER SUPPLY

Operating Voltage Range 90 - 264 VAC Rated Voltage Range 100-240V AC **Rated Line Frequency** 50/60 HZ **Operating Line Frequency** 47 - 63 Hz **Rated Input Current** 180 W: <2.3A 260 W: ≦3.1A

350 W: <4A 500 W: <6A

Rated Input Current with Energy Efficient* Power

Supply

180 W active PFC 87/90/87% efficient at 20/50/100% load (115 V)

88/92/88% efficient at 20/50/100% load (230 V);

350 W active PFC

87/90/87% efficient at 20/50/100% load (115 V) 88/92/88% efficient at 20/50/100% load (230 V)

500W active PFC

87/90/87% efficient at 20/50/100% load (115 V) 88/92/88% efficient at 20/50/100% load (230 V)

DC Output +12 V

Current Leakage (NFPA 99:

2102)

Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or

that contact patients in normal use. Per section 10.3.5.1.

Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care

facility or that contact patients in normal use. Per section 10.3.5.1.

Power Supply Fan 180 W/350 W: 70*25mm (linear type)

500 W: 70x25mm (PWM type)



Technical Specifications – Weights and Dimensions

WEIGHT AND DIMENSIONS

Chassis (W x D x H) 6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm) (w/ bezel)

System Volume 15.1 L

System Weight* 10.4 lb / 4.7 kg

 Packaged
 11.3 x 15.75 x 19.65 in

 (H x W x D)
 287 x 400 x 499 mm

Shipping Weight 17.64lb / 8 kg

Palletization 6 units per layer

Profile 7layer max
42 per pallet

42 per pall Footprint

-85.31x39.37x47.24 in (2167 x 1000 x1200 mm)



After-Market Options (availability may vary by region)

AFTERMARKET OPTIONS

Туре	Description	Part #
Memory	HP 4GB DDR4-3200 DIMM	13L78AA
	HP 8GB DDR4-3200 DIMM	13L76AA
	HP 16GB DDR4-3200 DIMM	13L74AA
	HP 32GB DDR4-3200 DIMM	13L72AA
Storage	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51AA
	HP PCIe NVME TLC 512GB SSD M.2 Drive	X8U75AA
	HP PCIe Gen 4 NVME TLC M.2 512GB SSD	406L8AA
	HP PCIe Gen 4 NVME TLC M.2 1TB SSD	406L7AA
	HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive	QK555AA
Graphics	NVIDIA T400 4GB GDDR6 3mDP	5Z7E0AA
Security	HP Business PC Security Lock V3 Kit	3XJ17AA
	HP Keyed Cable Lock 10mm kit	T1A62AA
Cables/Adapters	HP HDMI Standard Cable Kit	T6F94AA
	HP USB to Serial Port Adapter	J7B60AA
	HP PCIe x1 Parallel Port Card	N1M40AA
Networking	Intel Ethernet I225-T1 GbE NIC Card	406L9AA
Input	HP Wired Desktop 320K Keyboard	9SR37AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP 125 Wired Keyboard	266C9AA
	HP 125 Wired Mouse	265A9AA
	HP 128 Laser Wired Mouse	265D9AA
	HP Wired Desktop 320MK Mouse and Keyboard Combo	9SR36AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 225 Antimicrobial Wired Mouse and Keyboard Combo	286K3AA
Others	HP S101 Speaker bar	5UU40AA



Change Log

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Date of change:	Version History:	Change	Description of change:
June 13, 2023	From v1 to v2	Removal	Disclaimer from call outs front image, page 1
June 14, 2023	From V2 to V3	Removal	Call outs section, page 4
June 20, 2023	From V3 to V4	Correction	All call out images, ports and bays corrected
August 8, 2023	From V4 to V5	Update	Environmental section updated
August 17, 2023	From V5 to V6	Update	Back call outs image updated
August 21, 2023	From V6 to V7	Addition	Serial port (optional) added to Rear ports section
	From V7 to V8		
	From V8 to V9		
	From V9 to V10		
	From v10 to v11		
	From v11 to v12		
	From v12 to v13		
	From v13 to v14		

